

[Title of Invention] COPPER ALLOY FINE WIRE FOR BALL BONDING

[Title of Document] Abstract

[Problem] The present invention is made in order to solve the problems of bending of a tail wire within a capillary and bending of a wire tip when a wire is pulled upwards as it is after the second bonding and is cut, and an object of the present invention is to provide a copper alloy bonding wire which is free from bending of a tail wire by adding nickel (Ni) to a copper-phosphorus alloy.

[Construction] The copper alloy fine wire for ball bonding according to the present invention contains 0.02 mass% or more and 2 mass% or less of nickel (Ni), 5 mass ppm or more and 800 mass ppm or less of phosphorus (P), less than 100 mass ppm in total of other base metal elements and the remainder of copper (Cu).

[Representative Drawing] Fig. 2